

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



In re application of:

VICTOR TAN CHER 'KHNG
LEE KIAN CHAI

Serial No. 10/023,049

Art Unit: 2822

Filing Date: 12/20/2001

Examiner: Graybill, David

For: Semiconductor Package Having
Substrate With Multi-Layer
Metal Bumps

Attorney Docket No. 00-1117

AMENDMENT SUBMITTED WITH REQUEST FOR CONTINUED
EXAMINATION (RCE) UNDER 37 CFR 1.114

September 22, 2005

Mail Stop RCE
Commissioner For Patents
PO Box 1450
Alexandria, VA 22313-1450

Sir:

This Amendment is in response to the Office Action dated 06/22/2005, having a statutory period for response set to expire on 09/22/2005. Please amend the case as follows.

09/27/2005 BABRAHA1 00000009 10023049

02 FC:1202
03 FC:1201

200.00 OP
400.00 OP